

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings of claims in the application:

#### **Listing of Claims:**

Claims 1-21 (Canceled)

Claim 22 (Currently Amended): A method of manufacturing a semiconductor device, comprising:

placing a lead frame having a semiconductor element mounted thereon,  
between a top-half mold and a bottom-half mold;

introducing resin into a cavity formed by the top-half mold and the bottom-half mold; and

reducing a pressure in the cavity by extracting air from the cavity when a specified amount of resin has been supplied to the cavity,

wherein said introducing resin comprises forcing the resin into the cavity using a plunger,

the method further comprising detecting a position of the plunger to determine when the specified amount of resin has been supplied to the cavity.

Claim 23 (Previously Presented): The method of manufacturing a semiconductor device,

of claim 22, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

Claim 24 (Canceled)

Claim 25 (Currently Amended): ~~[[The]]~~ A method of manufacturing a semiconductor device ~~of claim 22, comprising:~~

placing a lead frame having a semiconductor element mounted thereon,  
between a top-half mold and a bottom-half mold;  
introducing resin into a cavity formed by the top-half mold and the bottom-half  
mold; and  
reducing a pressure in the cavity by extracting air from the cavity when a  
specified amount of resin has been supplied to the cavity,

wherein said introducing resin comprises forcing the resin into the cavity using a plunger,

the method further comprising detecting an amount of time the plunger is driven to determine when the specified amount of resin has been supplied to the cavity.

Claim 26 (Previously Presented): The method of manufacturing a semiconductor device of claim 22, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.

Claim 27 (Previously Presented): A method of manufacturing a semiconductor device, comprising:

placing a lead frame having a semiconductor element mounted thereon,  
between a top-half mold and a bottom-half mold;

introducing resin into a cavity formed by the top-half mold and the bottom-half mold using a plunger; and

reducing a pressure in the cavity by extracting air from the cavity according to an amount of time the plunger is driven.

Claim 28 (Previously Presented): The method of manufacturing a semiconductor device of claim 27, wherein said reducing a pressure in the cavity begins once the plunger is driven an amount of time necessary to introduce an amount of resin that fills about one half of the cavity.

Claim 29 (Previously Presented): The method of manufacturing a semiconductor device of claim 27, wherein said reducing a pressure in the cavity begins once the plunger is driven an amount of time necessary for the resin that is introduced into the cavity to begin hardening.

Claim 30 (Previously Presented): A method of manufacturing semiconductor device

packages comprising:

providing a transfer molding apparatus including a top-half mold and a bottom-half mold that forms a cavity as a molding space for a package, a transfer pot as a resin loading space, and a plunger that communicates with the transfer pot to force resin out of the pot and into the cavity;

placing a lead frame having a semiconductor element mounted thereon between the top-half mold and the bottom-half mold within the cavity;

introducing resin into the cavity using the plunger; and

reducing a pressure in the cavity using a pressure adjuster to extract air from the cavity when a specified amount of resin has been introduced to the cavity, to form a semiconductor device package.

Claim 31 (Previously Presented): The method of manufacturing semiconductor device packages of claim 30, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

Claim 32 (Previously Presented): The method of manufacturing semiconductor device packages of claim 30, further comprising detecting a position of the plunger to determine when the specified amount of resin has been introduced to the cavity.

Claim 33 (Previously Presented): The method for manufacturing semiconductor device

packages of claim 30, further comprising detecting an amount of time the plunger is driven to determine when the specified amount of resin has been introduced to the cavity.

Claim 34 (Previously Presented): The method of manufacturing semiconductor device packages of claim 30, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.